

**AMENDMENTS TO THE CLAIMS**

1. (Currently Amended) An abrasive slurry having dispersion stability, ~~comprising~~  
consisting essentially of:

abrasive fine particles made of one or more kinds of oxides;

colloidal fine particles made of colloidal oxide with an average particle size smaller than  
an average particle size of the abrasive fine particles; and

a dispersion medium in which the abrasive fine particles and the colloidal fine particles  
are dispersed;

wherein the average particle size ( $D_p$ ) of the abrasive fine particles is 100 to 5,000 nm,  
the average particle size ( $D_c$ ) of the colloidal fine particles is 10 to 300 nm, and a particle size  
ratio ( $D_c/D_p$ ) of the average particle size ( $D_c$ ) of the colloidal fine particles to the average  
particle size ( $D_p$ ) of the abrasive fine particles is 10 or less, and the abrasive fine particles have a  
particle concentration ( $C_p$ ) of 5 to 30 wt%, the colloidal fine particles have a particle  
concentration ( $C_c$ ) of 0.1 to 5 wt%, and a weight distribution ratio ( $C_c/C_p$ ) of the particle  
concentration ( $C_c$ ) of the colloidal fine particles to the particle concentration ( $C_p$ ) of the abrasive  
fine particles is 1 or less.

2-3. (Cancelled)

4. (Currently Amended) ~~An~~ The abrasive slurry having dispersion stability according to  
claim 1, wherein the dispersion medium comprises water or an aqueous dispersion medium  
mainly containing water.

5. (Currently Amended) ~~A~~ The abrasive slurry having dispersion stability according to claim 1, wherein the abrasive fine particles comprise a cerium oxide particle.

6. (Currently Amended) ~~A~~ The abrasive slurry having dispersion stability according to claim 1, wherein the colloidal fine particles comprise a colloidal silica.

7. (Previously Presented) A manufacturing method for a substrate as an inorganic substrate, comprising polishing the substrate using the abrasive slurry according to claim 1.

8. (Currently Amended) A The manufacturing method for a substrate according to claim 7, wherein the substrate has a surface on which an oxide film is formed.

9. (Currently Amended) ~~A~~ The abrasive slurry having dispersion stability according to any one of claims 1, 4, 5 and 6, wherein ~~an~~ no organic dispersant is ~~not essentially~~ contained therein.

10. (Previously Presented) A manufacturing method for a substrate as an inorganic substrate, comprising polishing the substrate using the abrasive slurry according to claim 9.